

IN THE SPECIFICATION

Please replace the paragraph beginning on page 5, line 6 with the following:

The semiconductor package according to the first embodiment of the present invention includes a substrate 100 comprising a redundant bond finger 204, an added bond finger 208, and a redundant solder ball pad 206, a semiconductor chip 102 mounted on the substrate 100, a plurality of normal wire bonding units 112[.],—one of which is a wire bonding unit 113 for connecting an added bond pad 202 to the redundant bond finger 204, an added wire bonding unit 114 that connects the redundant bond finger 204 to the added bond finger 208 that is in turn connected to the redundant solder ball pad 206 via printed circuit pattern 209, an encapsulant 210 for encapsulating the semiconductor chip 102, the normal wire bonding unit 112, and the added wire bonding unit 114, and a solder ball ~~118~~ connected to the redundant solder ball pad under the substrate 100. A plurality of solder ball pads 108 are connected to bond fingers 104 in a printed circuit pattern 106. As used herein, the term “wire bond” means a wire that electrically connects one contact to another above the surface of substrate 100, e.g., like wire bonds 112, 114 in Fig. 6.

Please replace the paragraph beginning on page 5, line 30 with the following:

Referring to FIG. 5, a semiconductor chip 102 having a plurality of bond pads 110 and an added bond pad 202 is attached to a package substrate 100 using an adhesive 116, e.g., die attach paste, of FIG. 6. Subsequently, a normal wire bonding unit 112 is formed to connect the added bond pad 202 to the redundant bond finger 204 of the substrate 100. Also, an added wire bonding unit 114 is formed to connect the redundant bond finger 204 to the added bond finger 208.